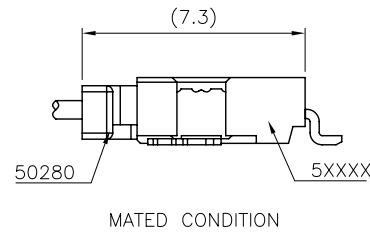
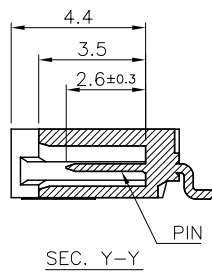
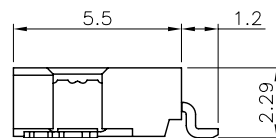


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



NOTES:

- MATERIAL:
 - HOUSING: HALOGEN FREE PLASTIC, UL94V-0.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
- FINISH:
 - CONTACT:
 - 50u" MIN NICKEL UNDER PLATING OVER ALL GOLD FLASH ON CONTACT AREA
 - 50u" MIN NICKEL UNDER PLATING OVER ALL 10u" MIN GOLD ON CONTACT AREA
 - SOLDER:
 - 50u" MIN NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 50u" MIN NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - FITTING NAIL:
 - 50u" MIN NICKEL UNDER PLATING OVER ALL 100u" MIN MATT TIN OVER ALL
- REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
- SPEC. PLS. REFER TO PS-50278-xxxx-xxx
- PACKAGE PLS. REFER TO 51377-xxxx-xx-TRP
- PART NUMBER

51377-XXXXX-001

NO OF CKT

XXX	Description
001	WHITE HF PLASTICS

PACKING
0:TAPE REEL

PLATING
1:GOLD FLASH OVERALL
T: 10u" GOLD ON CONTACT

CKT.	Dim A	Dim B	Dim C	Dim D
9	10.00	16.40	11.55	8.75

一般公差 TOLERANCES X ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°	宏致電子股份有限公司 Aces Electronics Co.,Ltd.	
檢驗尺寸標示 SYMBOLS INDICATE CLASSIFICATION DIMENSION MARK IS CRITICAL DIM. MARK IS MAJOR DIM.	品名 (TITLE) 1.25mm Pitch WTB Wafer Conn. SMT S/R R/A Type	製圖 (DR) 17/09/06 SHI, YANAN 審核 (CHKD) BRAVE 核准 (APPD) FRANK
表面處理 (FINISH)	圖號 (DWG NO.) 51377-XXXXX-XXX	張數 (SHEET) 1 OF 1 單位 (UNITS) mm 比例 (SCALE) 1:1 單位 (UNITS) mm 比例 (SCALE) 1:1